Product Change Notification / DSNO-04XWNP597

Date:

15-Mar-2024

Product Category:

Broadband Gateway

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6837 Initial Notice: Qualification of new die size (131.5 x 76.1mils) for Die #1 of selected Microsemi LE9642PQC, LE9642PQCT, LE9652PQC, ZL88107LDG1, LE9652PQCT and ZL88107LDF1 catalog part numbers (CPN) available in 48L VQFN (7x7x1mm) package.

Affected CPNs:

DSNO-04XWNP597_Affected_CPN_03152024.pdf
DSNO-04XWNP597_Affected_CPN_03152024.csv

Notification Text:

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of new die size (131.5 x 76.1mils) for Die #1 of selected Microsemi LE9642PQC, LE9642PQCT, LE9652PQC, ZL88107LDG1, LE9652PQCT and ZL88107LDF1 catalog part numbers (CPN) available in 48L VQFN (7x7x1mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change

Fabrication Location	Die # 1	Global Foundries - Fab 7; Singapore (12") (GF07)	Global Foundries - Fab 7; Singapore (12") (GF07)
	Die # 2	Global Foundries - Fab 2; Singapore (8") (GF02)	Global Foundries - Fab 2; Singapore (8") (GF02)
Die Size	Die # 1	142x89 mils	131.5x76.1 mils
		Please see attached pre and post change comparison for Die # 1 Location	
	Die # 2	No Change	No Change
Assembly Site		Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)
Wire Material		CuPdAu	CuPdAu
Die Attach Material		3280	QMI519
Molding Compound Material		G700LTD	G700LTD
Lead Frame Material		A194	A194
Lead Frame DAP Surface Prep		Ag selective Plated	Ag Double Ring Plated
Lead Frame Lead Lock		Yes	No
Lead Frame Paddle Size		232 x 232 mils	220 x 220 mils

Impacts to Data Sheet: None

Change Impact None

Reason for Change: To improve productivity by qualifying a new die size.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: July 2024

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	March 2024					>	July 2024				
Workweek	09	10	11	12	13		27	28	29	30	31
Initial PCN Issue Date			x								
Qual Report Availability											x
Final PCN Issue Date											x

Method to Identify Change: Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: March 15, 2024: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_DSNO-04XWNP597_Pre and Post Change Summary.pdf
PCN_DSNO-04XWNP597_Qual_Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

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